

List of Publications: 1.7.2008 – 31.12.2009

1. European Nanoelectronics Forum 2008 (ENIAC), December 2-3, 2008, Paris, FR by Process Relations
2. 7th GI/GMM/ITG workshop, February 3, 2009, Ulm, DE by Coventor: introduction of EDA-compatible methodology for design and simulation of MEMS with IC
3. New Materials Forum, March 5-6, 2009, Valencia, ES by Process Relations
4. Smart Systems Integration, March 10-11, 2009, Brussels, BE by ITE: „Reliability Issues in Modeling and Simulations of the Heterogeneous Integrated Systems“
5. May 11, 2009, MikroMedia No. 44: “Design solution for MEMS and IC products” and “Process Relations signs up AMO for its XperiDesk process management software”
6. May 18, 2009, 2. Article in EETimes: Turnkey environment allows MEMS/IC co-design, co-verification and corresponding movie related to Coventor-Cadence Partnership
7. CDN Live 2009 Conference, May 18-20, 2009, Munich, DE: presentation „MEMS-IC Common Platform“ by Gunar Lorenz, Coventor awarded with the „Best Paper Award“
8. 20th IEEE/SEMI Advanced Semiconductor Manufacturing (ASMC) conference proceedings May 2009 by X-FAB and Coventor: paper presentation „3D Process Modelling – A Novel and Efficient Tool for MEMS Foundry Design Support
9. 2009 COLLOQUE NATIONAL DU GDR SOC-SIP, 10-12 June, 2009, Orsay, FR, Presentation (Invited) „Convergence des flots de conception MEMS/EDA“ by Gerold Schropfer, Coventor
10. 8th Symposium Diagnostics & Yield Advanced Silicon Devices and Technologies for ULSI Era, June 22-24, 2009, Warsaw, PL by ITE: „Multi-domain Modeling and Simulations of the Heterogeneous Systems“
11. MIXDES – 16th International Conference Mixed Design of Integrated Circuits and Systems, June 25-27, 2009, Łódź, PL by ITE: „Thermo-Mechanical Aspects of Reliability for Vertically Integrated Heterogeneous Systems“
12. COMS, August 30-September 3, 2009, Copenhagen, Denmark: presentation by PR
13. MicroMechanics Europe 2009 (MME09), 20-22 September 2009, Toulouse, FR, presentation (Invited) „From Physical to System-Level Design: Current and Next Generations of MEMS Design Tools“ by Gerold Schropfer, Coventor
14. IEEE International 3D Systems Conference 2009, September 28-30, 2009: Reliability aspects of 3D-oriented heterogeneous device related to stress sensitivity of MOS transistors by Grzegorz Janczyk, ITE
15. International MEMS/MST Industry Forum at Semicon Europa, October 6, 2009: MEMS/MST Collaborative Product Engineering for Silicon-based Fabrication Process Development by Dirk Ortloff, Process Relations GmbH
16. International MEMS/MST Industry Forum at Semicon Europa, October 6, 2009: 3-D Process Modelling - A Novel and Efficient Tool for MEMS Foundry Design Support by Gisbert Hölzer, X-FAB
17. 15th International Workshop on Thermal investigations of ICs and Systems, Leuven, Belgium October 7-9, 2009: poster, conference proceedings, submission for Microelectronic Journal: Thermo-Mechanical Reliability Loop In Device Modeling by Tomasz Bieniek, ITE
18. 4th International Conference on Advanced Research and Rapid Prototyping, Leiria, Portugal, October 6 – 10, 2009, Presentation: A holistic approach for customer-oriented product engineering of micro devices, Kai Hahn, USI